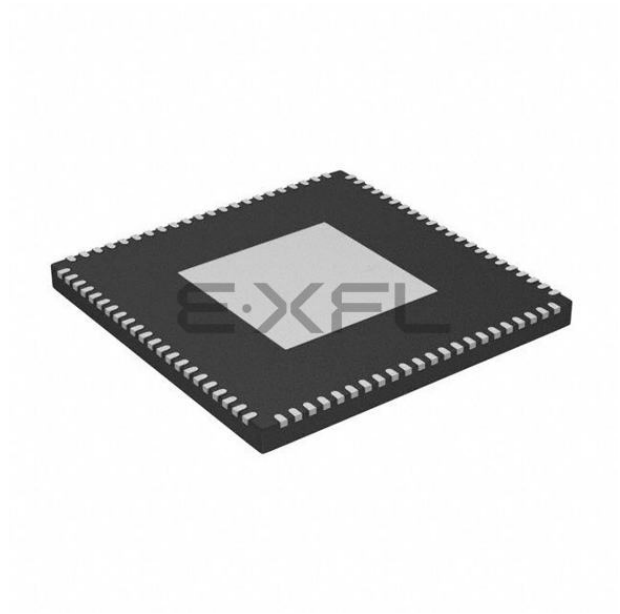

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Understanding Embedded - DSP (Digital Signal Processors)

Embedded - DSP (Digital Signal Processors) are specialized microprocessors designed to perform complex mathematical computations on digital signals in real-time. Unlike general-purpose processors, DSPs are optimized for high-speed numeric processing tasks, making them ideal for applications that require efficient and precise manipulation of digital data. These processors are fundamental in converting and processing signals in various forms, including audio, video, and communication signals, ensuring that data is accurately interpreted and utilized in embedded systems.

Applications of Embedded - DSP (Digital Signal Processors)

Details	
Product Status	Active
Type	Blackfin+
Interface	CAN, DSPI, EBI/EMI, I²C, PPI, QSPI, SD/SDIO, SPI, SPORT, UART/USART, USB OTG
Clock Rate	300MHz
Non-Volatile Memory	ROM (512kB)
On-Chip RAM	512kB
Voltage - I/O	1.8V, 3.3V
Voltage - Core	1.10V
Operating Temperature	-40°C ~ 105°C (TA)
Mounting Type	Surface Mount
Package / Case	88-VFQFN Exposed Pad, CSP
Supplier Device Package	88-LFCSP-VQ (12x12)
Purchase URL	https://www.e-xfl.com/product-detail/analog-devices/adbf704wccpz311

BLACKFIN+ PROCESSOR CORE

As shown in Figure 1, the processor integrates a Blackfin+ processor core. The core, shown in Figure 2, contains two 16-bit multipliers, one 32-bit multiplier, two 40-bit accumulators (which may be used together as a 72-bit accumulator), two 40-bit ALUs, one 72-bit ALU, four video ALUs, and a 40-bit shifter. The computation units process 8-, 16-, or 32-bit data from the register file.

The compute register file contains eight 32-bit registers. When performing compute operations on 16-bit operand data, the register file operates as 16 independent 16-bit registers. All operands for compute operations come from the multiported register file and instruction constant fields.

The core can perform two 16-bit by 16-bit multiply-accumulates or one 32-bit multiply-accumulate in each cycle. Signed and unsigned formats, rounding, saturation, and complex multiplies are supported.

The ALUs perform a traditional set of arithmetic and logical operations on 16-bit or 32-bit data. In addition, many special instructions are included to accelerate various signal processing tasks. These include bit operations such as field extract and population count, divide primitives, saturation and rounding, and sign/exponent detection. The set of video instructions include byte alignment and packing operations, 16-bit and 8-bit adds with clipping, 8-bit average operations, and 8-bit subtract/absolute value/accumulate (SAA) operations. Also provided are the compare/select and vector search instructions.

For certain instructions, two 16-bit ALU operations can be performed simultaneously on register pairs (a 16-bit high half and 16-bit low half of a compute register). If a second ALU is used, quad 16-bit operations are possible.

The 40-bit shifter can perform shifts and rotates and is used to support normalization, field extract, and field deposit instructions.

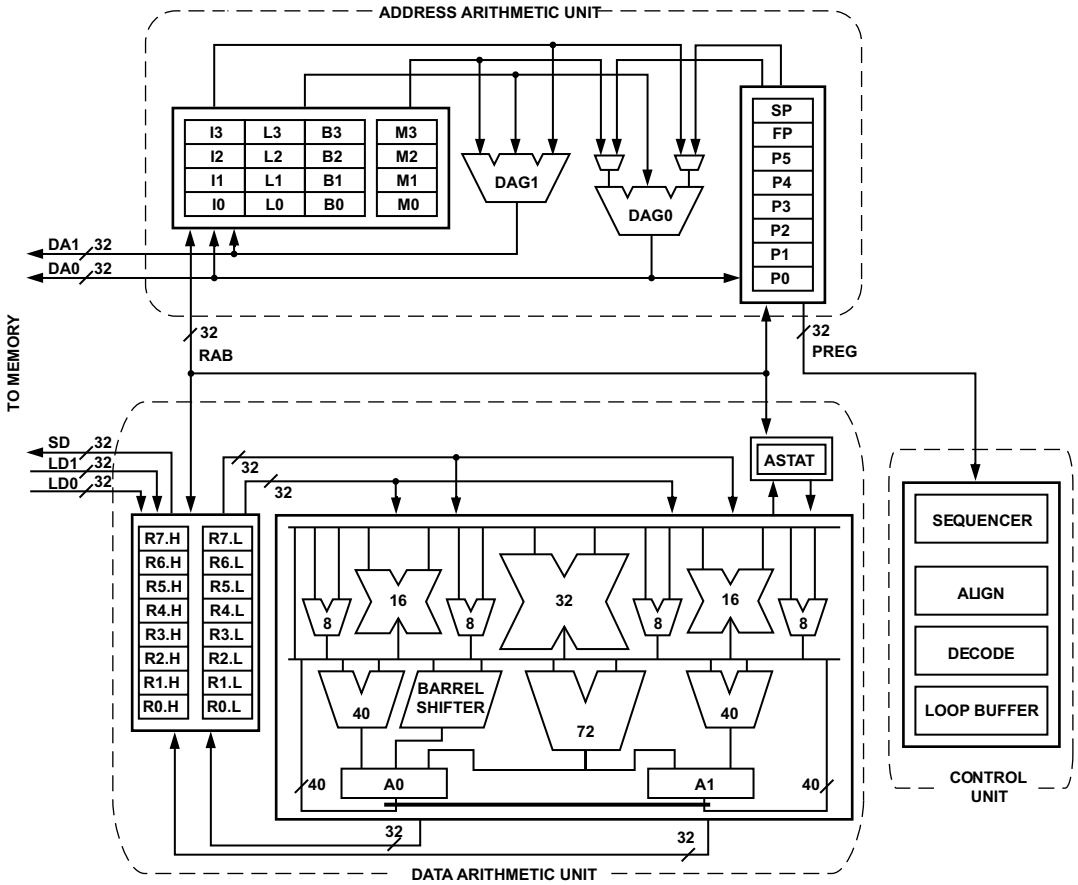


Figure 2. Blackfin+ Processor Core

- A similar buffer that interrupts on fractional buffers (for example, 1/2, 1/4).
- 1D DMA—uses a set of identical ping-pong buffers defined by a linked ring of two-word descriptor sets, each containing a link pointer and an address.
- 1D DMA—uses a linked list of 4 word descriptor sets containing a link pointer, an address, a length, and a configuration.
- 2D DMA—uses an array of one-word descriptor sets, specifying only the base DMA address.
- 2D DMA—uses a linked list of multi-word descriptor sets, specifying everything.

Event Handling

The processor provides event handling that supports both nesting and prioritization. Nesting allows multiple event service routines to be active simultaneously. Prioritization ensures that servicing of a higher-priority event takes precedence over servicing of a lower-priority event. The processor provides support for five different types of events:

- Emulation—An emulation event causes the processor to enter emulation mode, allowing command and control of the processor through the JTAG interface.
- Reset—This event resets the processor.
- Nonmaskable interrupt (NMI)—The NMI event can be generated either by the software watchdog timer, by the $\overline{\text{NMI}}$ input signal to the processor, or by software. The NMI event is frequently used as a power-down indicator to initiate an orderly shutdown of the system.
- Exceptions—Events that occur synchronously to program flow (in other words, the exception is taken before the instruction is allowed to complete). Conditions such as data alignment violations and undefined instructions cause exceptions.
- Interrupts —Events that occur asynchronously to program flow. They are caused by input signals, timers, and other peripherals, as well as by an explicit software instruction.

System Event Controller (SEC)

The SEC manages the enabling, prioritization, and routing of events from each system interrupt or fault source. Additionally, it provides notification and identification of the highest priority active system interrupt request to the core and routes system fault sources to its integrated fault management unit. The SEC triggers core general-purpose interrupt IVG11. It is recommended that IVG11 be set to allow self-nesting. The four lower priority interrupts (IVG15-12) may be used for software interrupts.

Trigger Routing Unit (TRU)

The TRU provides system-level sequence control without core intervention. The TRU maps trigger masters (generators of triggers) to trigger slaves (receivers of triggers). Slave endpoints can be configured to respond to triggers in various ways. Common applications enabled by the TRU include:

- Automatically triggering the start of a DMA sequence after a sequence from another DMA channel completes
- Software triggering
- Synchronization of concurrent activities

General-Purpose I/O (GPIO)

Each general-purpose port pin can be individually controlled by manipulation of the port control, status, and interrupt registers:

- GPIO direction control register—Specifies the direction of each individual GPIO pin as input or output.
- GPIO control and status registers—A write one to modify mechanism allows any combination of individual GPIO pins to be modified in a single instruction, without affecting the level of any other GPIO pins.
- GPIO interrupt mask registers—Allow each individual GPIO pin to function as an interrupt to the processor. GPIO pins defined as inputs can be configured to generate hardware interrupts, while output pins can be triggered by software interrupts.
- GPIO interrupt sensitivity registers—Specify whether individual pins are level- or edge-sensitive and specify—if edge-sensitive—whether just the rising edge or both the rising and falling edges of the signal are significant.

Pin Interrupts

Every port pin on the processor can request interrupts in either an edge-sensitive or a level-sensitive manner with programmable polarity. Interrupt functionality is decoupled from GPIO operation. Three system-level interrupt channels (PINT0–3) are reserved for this purpose. Each of these interrupt channels can manage up to 32 interrupt pins. The assignment from pin to interrupt is not performed on a pin-by-pin basis. Rather, groups of eight pins (half ports) can be flexibly assigned to interrupt channels.

Every pin interrupt channel features a special set of 32-bit memory-mapped registers that enable half-port assignment and interrupt management. This includes masking, identification, and clearing of requests. These registers also enable access to the respective pin states and use of the interrupt latches, regardless of whether the interrupt is masked or not. Most control registers feature multiple MMR address entries to write-one-to-set or write-one-to-clear them individually.

Pin Multiplexing

The processor supports a flexible multiplexing scheme that multiplexes the GPIO pins with various peripherals. A maximum of 4 peripherals plus GPIO functionality is shared by each GPIO pin. All GPIO pins have a bypass path feature—that is, when the

Serial Peripheral Interface (SPI) Ports

The processors have three industry-standard SPI-compatible ports that allow it to communicate with multiple SPI-compatible devices.

The baseline SPI peripheral is a synchronous, four-wire interface consisting of two data pins, one device select pin, and a gated clock pin. The two data pins allow full-duplex operation to other SPI-compatible devices. An additional two (optional) data pins are provided to support quad SPI operation. Enhanced modes of operation such as flow control, fast mode, and dual I/O mode (DIOM) are also supported. In addition, a direct memory access (DMA) mode allows for transferring several words with minimal CPU interaction.

With a range of configurable options, the SPI ports provide a glueless hardware interface with other SPI-compatible devices in master mode, slave mode, and multimaster environments. The SPI peripheral includes programmable baud rates, clock phase, and clock polarity. The peripheral can operate in a multimaster environment by interfacing with several other devices, acting as either a master device or a slave device. In a multimaster environment, the SPI peripheral uses open-drain outputs to avoid data bus contention. The flow control features enable slow slave devices to interface with fast master devices by providing an SPI Ready pin which flexibly controls the transfers.

The SPI port's baud rate and clock phase/polarities are programmable, and it has integrated DMA channels for both transmit and receive data streams.

SPI Host Port (SPIHP)

The processor includes one SPI host port which may be used in conjunction with any available SPI port to enhance its SPI slave mode capabilities. The SPIHP allows a SPI host device access to memory-mapped resources of the processor through a SPI SRAM/FLASH style protocol. The following features are included:

- Direct read/write of memory and memory-mapped registers
- Support for pre-fetch for faster reads
- Support for SPI controllers that implement hardware-based SPI memory protocol
- Error capture and reporting for protocol errors, bus errors, and over/underflow

UART Ports

The processor provides two full-duplex universal asynchronous receiver/transmitter (UART) ports, which are fully compatible with PC-standard UARTs. Each UART port provides a simplified UART interface to other peripherals or hosts, supporting full-duplex, DMA-supported, asynchronous transfers of serial data. A UART port includes support for five to eight data bits, and none, even, or odd parity. Optionally, an additional address bit can be transferred to interrupt only addressed nodes in multi-drop bus (MDB) systems. A frame is terminated by a configurable number of stop bits.

The UART ports support automatic hardware flow control through the clear to send (CTS) input and request to send (RTS) output with programmable assertion FIFO levels.

To help support the local interconnect network (LIN) protocols, a special command causes the transmitter to queue a break command of programmable bit length into the transmit buffer. Similarly, the number of stop bits can be extended by a programmable inter-frame space.

The capabilities of the UARTs are further extended with support for the Infrared Data Association (IrDA®) serial infrared physical layer link specification (SIR) protocol.

2-Wire Controller Interface (TWI)

The processor includes a 2-wire interface (TWI) module for providing a simple exchange method of control data between multiple devices. The TWI module is compatible with the widely used I^2C bus standard. The TWI module offers the capabilities of simultaneous master and slave operation and support for both 7-bit addressing and multimedia data arbitration. The TWI interface utilizes two pins for transferring clock (TWI_SCL) and data (TWI_SDA) and supports the protocol at speeds up to 400k bits/sec. The TWI interface pins are compatible with 5 V logic levels.

Additionally, the TWI module is fully compatible with serial camera control bus (SCCB) functionality for easier control of various CMOS camera sensor devices.

Mobile Storage Interface (MSI)

The mobile storage interface (MSI) controller acts as the host interface for multimedia cards (MMC), secure digital memory cards (SD), and secure digital input/output cards (SDIO). The following list describes the main features of the MSI controller:

- Support for a single MMC, SD memory, and SDIO card
- Support for 1-bit and 4-bit SD modes
- Support for 1-bit, 4-bit, and 8-bit MMC modes
- Support for eMMC 4.5 embedded NAND flash devices
- Support for power management and clock control
- An eleven-signal external interface with clock, command, optional interrupt, and up to eight data lines
- Card interface clock generation from SCLK0 or SCLK1
- SDIO interrupt and read wait features

Controller Area Network (CAN)

A CAN controller implements the CAN 2.0B (active) protocol. This protocol is an asynchronous communications protocol used in both industrial and automotive control systems. The CAN protocol is well suited for control applications due to its capability to communicate reliably over a network. This is because the protocol incorporates CRC checking, message error tracking, and fault node confinement.

184-BALL CSP_BGA SIGNAL DESCRIPTIONS

The processor's pin definitions are shown in Table 7. The columns in this table provide the following information:

- Signal Name: The Signal Name column in the table includes the signal name for every pin and (where applicable) the GPIO multiplexed pin function for every pin.
- Description: The Description column in the table provides a verbose (descriptive) name for the signal.
- General-Purpose Port: The Port column in the table shows whether or not the signal is multiplexed with other signals on a general-purpose I/O port pin.
- Pin Name: The Pin Name column in the table identifies the name of the package pin (at power on reset) on which the signal is located (if a single function pin) or is multiplexed (if a general-purpose I/O pin).

Table 7. ADSP-BF70x 184-Ball CSP_BGA Signal Descriptions

Signal Name	Description	Port	Pin Name
CAN0_RX	CAN0 Receive	C	PC_02
CAN0_TX	CAN0 Transmit	C	PC_03
CAN1_RX	CAN1 Receive	A	PA_12
CAN1_TX	CAN1 Transmit	A	PA_13
CNT0_DG	CNT0 Count Down and Gate	A	PA_07
CNT0_UD	CNT0 Count Up and Direction	A	PA_15
CNT0_ZM	CNT0 Count Zero Marker	A	PA_13
DMC0_A00	DMC0 Address 0	Not Muxed	DMC0_A00
DMC0_A01	DMC0 Address 1	Not Muxed	DMC0_A01
DMC0_A02	DMC0 Address 2	Not Muxed	DMC0_A02
DMC0_A03	DMC0 Address 3	Not Muxed	DMC0_A03
DMC0_A04	DMC0 Address 4	Not Muxed	DMC0_A04
DMC0_A05	DMC0 Address 5	Not Muxed	DMC0_A05
DMC0_A06	DMC0 Address 6	Not Muxed	DMC0_A06
DMC0_A07	DMC0 Address 7	Not Muxed	DMC0_A07
DMC0_A08	DMC0 Address 8	Not Muxed	DMC0_A08
DMC0_A09	DMC0 Address 9	Not Muxed	DMC0_A09
DMC0_A10	DMC0 Address 10	Not Muxed	DMC0_A10
DMC0_A11	DMC0 Address 11	Not Muxed	DMC0_A11
DMC0_A12	DMC0 Address 12	Not Muxed	DMC0_A12
DMC0_A13	DMC0 Address 13	Not Muxed	DMC0_A13
DMC0_BA0	DMC0 Bank Address Input 0	Not Muxed	DMC0_BA0
DMC0_BA1	DMC0 Bank Address Input 1	Not Muxed	DMC0_BA1
DMC0_BA2	DMC0 Bank Address Input 2	Not Muxed	DMC0_BA2
$\overline{\text{DMC0\_CAS}}$	DMC0 Column Address Strobe	Not Muxed	$\overline{\text{DMC0\_CAS}}$
DMC0_CK	DMC0 Clock	Not Muxed	DMC0_CK
DMC0_CKE	DMC0 Clock enable	Not Muxed	DMC0_CKE
$\overline{\text{DMC0\_CK}}$	DMC0 Clock (complement)	Not Muxed	$\overline{\text{DMC0\_CK}}$
$\overline{\text{DMC0\_CS0}}$	DMC0 Chip Select 0	Not Muxed	$\overline{\text{DMC0\_CS0}}$
DMC0_DQ00	DMC0 Data 0	Not Muxed	DMC0_DQ00
DMC0_DQ01	DMC0 Data 1	Not Muxed	DMC0_DQ01
DMC0_DQ02	DMC0 Data 2	Not Muxed	DMC0_DQ02
DMC0_DQ03	DMC0 Data 3	Not Muxed	DMC0_DQ03
DMC0_DQ04	DMC0 Data 4	Not Muxed	DMC0_DQ04
DMC0_DQ05	DMC0 Data 5	Not Muxed	DMC0_DQ05
DMC0_DQ06	DMC0 Data 6	Not Muxed	DMC0_DQ06

GPIO MULTIPLEXING FOR 184-BALL CSP_BGA

Table 8 through Table 10 identify the pin functions that are multiplexed on the general-purpose I/O pins of the 184-ball CSP_BGA package.

Table 8. Signal Multiplexing for Port A

Signal Name	Multiplexed Function 0	Multiplexed Function 1	Multiplexed Function 2	Multiplexed Function 3	Multiplexed Function Input Tap
PA_00	SPI1_CLK		TRACE0_D07	SMC0_ABE0	
PA_01	SPI1_MISO		TRACE0_D06	SMC0_ABE1	
PA_02	SPI1_MOSI		TRACE0_D05	SMC0_AMS1	
PA_03	SPI1_SEL2	SPI1_RDY		SMC0_ARDY	
PA_04	SPI1_SEL1	TM0_TMR7	SPI2_RDY	SMC0_A08	SPI1_SS
PA_05	TM0_TMR0	SPI0_SEL1		SMC0_A07	SPI0_SS
PA_06	TM0_TMR1	SPI0_SEL2	SPI0_RDY	SMC0_A06	
PA_07	TM0_TMR2	SPT1_BTDV	SPT1_ATDV	SMC0_A05	CNT0_DG
PA_08	PPI0_D11	MSI0_CD	SPT1_ACLK	SMC0_A01	
PA_09	PPI0_D10	TM0_TMR4	SPT1_AFS	SMC0_A02	
PA_10	PPI0_D09	TM0_TMR5	SPT1_AD0	SMC0_A03	
PA_11	PPI0_D08	TM0_TMR6	SPT1_AD1	SMC0_A04	
PA_12	PPI0_FS1	CAN1_RX	SPT0_AFS	SMC0_AOE	TM0_ACI6/SYS_WAKE4
PA_13	PPI0_FS2	CAN1_TX	SPT0_ACLK	SMC0_ARE	CNT0_ZM
PA_14	PPI0_CLK	SPI1_SEL4	SPT0_AD0	SMC0_AWE	TM0_ACLK5
PA_15	PPI0_FS3	SPT0_ATDV	SPT0_BTDV	SMC0_AMS0	CNT0_UD

Table 9. Signal Multiplexing for Port B

Signal Name	Multiplexed Function 0	Multiplexed Function 1	Multiplexed Function 2	Multiplexed Function 3	Multiplexed Function Input Tap
PB_00	PPI0_D07	SPT1_BCLK	SPI0_CLK	SMC0_D07	TM0_ACLK3
PB_01	PPI0_D06	SPT1_BFS	SPI0_MISO	SMC0_D06	TM0_ACI1
PB_02	PPI0_D05	SPT1_BD0	SPI0_MOSI	SMC0_D05	
PB_03	PPI0_D04	SPT1_BD1	SPI0_D2	SMC0_D04	
PB_04	PPI0_D03	SPT0_BCLK	SPI0_SEL4	SMC0_D03	TM0_ACLK6
PB_05	PPI0_D02	SPT0_BD0	SPI0_SEL5	SMC0_D02	
PB_06	PPI0_D01	SPT0_BFS	SPI0_SEL6	SMC0_D01	TM0_CLK
PB_07	PPI0_D00	SPT0_BD1	SPI0_D3	SMC0_D00	SYS_WAKE0
PB_08	UART0_TX	PPI0_D16	SPI2_SEL2	SMC0_D08	SYS_WAKE1
PB_09	UART0_RX	PPI0_D17	SPI2_SEL3	SMC0_D09	TM0_ACI3
PB_10	SPI2_CLK		TRACE0_CLK	SMC0_D10	TM0_ACLK4
PB_11	SPI2_MISO		TRACE0_D04	SMC0_D11	
PB_12	SPI2_MOSI		TRACE0_D03	SMC0_D12	SYS_WAKE2
PB_13	SPI2_D2	UART1_RTS	TRACE0_D02	SMC0_D13	
PB_14	SPI2_D3	UART1_CTS	TRACE0_D01	SMC0_D14	
PB_15	SPI2_SEL1		TRACE0_D00	SMC0_D15	SPI2_SS

Table 10. Signal Multiplexing for Port C

Signal Name	Multiplexed Function 0	Multiplexed Function 1	Multiplexed Function 2	Multiplexed Function 3	Multiplexed Function Input Tap
PC_00	UART1_TX	SPT0_AD1	PPI0_D15		
PC_01	UART1_RX	SPT0_BD1	PPI0_D14	SMC0_A09	TM0_ACI4
PC_02	UART0_RTS	CAN0_RX	PPI0_D13	SMC0_A10	TM0_ACI5/SYS_ WAKE3
PC_03	UART0_CTS	CAN0_TX	PPI0_D12	SMC0_A11	TM0_ACI0
PC_04	SPT0_BCLK	SPI0_CLK	MSI0_D1	SMC0_A12	TM0_ACLK0
PC_05	SPT0_AFS	TM0_TMR3	MSI0_CMD		
PC_06	SPT0_BD0	SPI0_MISO	MSI0_D3		
PC_07	SPT0_BFS	SPI0_MOSI	MSI0_D2		TM0_ACI2
PC_08	SPT0_AD0	SPI0_D2	MSI0_D0		
PC_09	SPT0_ACLK	SPI0_D3	MSI0_CLK		TM0_ACLK2
PC_10	SPT1_BCLK	MSI0_D4	SPI1_SEL3		TM0_ACLK1
PC_11	SPT1_BFS	MSI0_D5	SPI0_SEL3		
PC_12	SPT1_BD0	MSI0_D6			
PC_13	SPT1_BD1	MSI0_D7			
PC_14	SPT1_BTDV	MSI0_INT			

12 mm × 12 mm 88-LEAD LFCSP (QFN) SIGNAL DESCRIPTIONS

The processor's pin definitions are shown in Table 11. The columns in this table provide the following information:

- Signal Name: The Signal Name column in the table includes the signal name for every pin and (where applicable) the GPIO multiplexed pin function for every pin.
- Description: The Description column in the table provides a verbose (descriptive) name for the signal.
- General-Purpose Port: The Port column in the table shows whether or not the signal is multiplexed with other signals on a general-purpose I/O port pin.
- Pin Name: The Pin Name column in the table identifies the name of the package pin (at power on reset) on which the signal is located (if a single function pin) or is multiplexed (if a general-purpose I/O pin).

Table 11. ADSP-BF70x 12 mm × 12 mm 88-Lead LFCSP (QFN) Signal Descriptions

Signal Name	Description	Port	Pin Name
CAN0_RX	CAN0 Receive	C	PC_02
CAN0_TX	CAN0 Transmit	C	PC_03
CAN1_RX	CAN1 Receive	A	PA_12
CAN1_TX	CAN1 Transmit	A	PA_13
CNT0_DG	CNT0 Count Down and Gate	A	PA_07
CNT0_UD	CNT0 Count Up and Direction	A	PA_15
CNT0_ZM	CNT0 Count Zero Marker	A	PA_13
GND	Ground	Not Muxed	GND
JTG_SWCLK	TAPC0 Serial Wire Clock	Not Muxed	JTG_TCK_SWCLK
JTG_SWDIO	TAPC0 Serial Wire DIO	Not Muxed	JTG_TMS_SWDIO
JTG_SWO	TAPC0 Serial Wire Out	Not Muxed	JTG_TDO_SWO
JTG_TCK	TAPC0 JTAG Clock	Not Muxed	JTG_TCK_SWCLK
JTG_TDI	TAPC0 JTAG Serial Data In	Not Muxed	JTG_TDI
JTG_TDO	TAPC0 JTAG Serial Data Out	Not Muxed	JTG_TDO_SWO
JTG_TMS	TAPC0 JTAG Mode Select	Not Muxed	JTG_TMS_SWDIO
$\overline{\text{JTG\_TRST}}$	TAPC0 JTAG Reset	Not Muxed	$\overline{\text{JTG\_TRST}}$
$\overline{\text{MSI0\_CD}}$	MSI0 Card Detect	A	PA_08
MSI0_CLK	MSI0 Clock	C	PC_09
MSI0_CMD	MSI0 Command	C	PC_05
MSI0_D0	MSI0 Data 0	C	PC_08
MSI0_D1	MSI0 Data 1	C	PC_04
MSI0_D2	MSI0 Data 2	C	PC_07
MSI0_D3	MSI0 Data 3	C	PC_06
MSI0_D4	MSI0 Data 4	C	PC_10
PA_00-PA_15	Position 00 through Position 15	A	PA_00-PA_15
PB_00-PB_15	Position 00 through Position 15	B	PB_00-PB_15
PC_00-PC_10	Position 00 through Position 10	C	PC_00-PC_10
PPI0_CLK	EPPI0 Clock	A	PA_14
PPI0_D00	EPPI0 Data 0	B	PB_07
PPI0_D01	EPPI0 Data 1	B	PB_06
PPI0_D02	EPPI0 Data 2	B	PB_05
PPI0_D03	EPPI0 Data 3	B	PB_04
PPI0_D04	EPPI0 Data 4	B	PB_03
PPI0_D05	EPPI0 Data 5	B	PB_02
PPI0_D06	EPPI0 Data 6	B	PB_01
PPI0_D07	EPPI0 Data 7	B	PB_00

Table 15. ADSP-BF70x Designer Quick Reference (Continued)

Signal Name	Type	Driver Type	Int Term	Reset Term	Reset Drive	Hiber Term	Hiber Drive	Power Domain	Description and Notes
DMC0_A06	I/O	B	none	none	none	none	none	VDD_DMC	Desc: DMC0 Address 6 Notes: No notes.
DMC0_A07	I/O	B	none	none	none	none	none	VDD_DMC	Desc: DMC0 Address 7 Notes: No notes.
DMC0_A08	I/O	B	none	none	none	none	none	VDD_DMC	Desc: DMC0 Address 8 Notes: No notes.
DMC0_A09	I/O	B	none	none	none	none	none	VDD_DMC	Desc: DMC0 Address 9 Notes: No notes.
DMC0_A10	I/O	B	none	none	none	none	none	VDD_DMC	Desc: DMC0 Address 10 Notes: No notes.
DMC0_A11	I/O	B	none	none	none	none	none	VDD_DMC	Desc: DMC0 Address 11 Notes: No notes.
DMC0_A12	I/O	B	none	none	none	none	none	VDD_DMC	Desc: DMC0 Address 12 Notes: No notes.
DMC0_A13	I/O	B	none	none	none	none	none	VDD_DMC	Desc: DMC0 Address 13 Notes: No notes.
DMC0_BA0	I/O	B	none	none	none	none	none	VDD_DMC	Desc: DMC0 Bank Address Input 0 Notes: No notes.
DMC0_BA1	I/O	B	none	none	none	none	none	VDD_DMC	Desc: DMC0 Bank Address Input 1 Notes: No notes.
DMC0_BA2	I/O	B	none	none	none	none	none	VDD_DMC	Desc: DMC0 Bank Address Input 2 Notes: For LPDDR, leave unconnected.
$\overline{\text{DMC0\_CAS}}$	I/O	B	none	none	none	none	none	VDD_DMC	Desc: DMC0 Column Address Strobe Notes: No notes.
DMC0_CK	I/O	C	none	none	L	none	L	VDD_DMC	Desc: DMC0 Clock Notes: No notes.
$\overline{\text{DMC0\_CK}}$	I/O	C	none	none	L	none	L	VDD_DMC	Desc: DMC0 Clock (complement) Notes: No notes.
DMC0_CKE	I/O	B	none	none	L	none	L	VDD_DMC	Desc: DMC0 Clock enable Notes: No notes.
$\overline{\text{DMC0\_CS0}}$	I/O	B	none	none	none	none	none	VDD_DMC	Desc: DMC0 Chip Select 0 Notes: No notes.
DMC0_DQ00	I/O	B	none	none	none	none	none	VDD_DMC	Desc: DMC0 Data 0 Notes: No notes.
DMC0_DQ01	I/O	B	none	none	none	none	none	VDD_DMC	Desc: DMC0 Data 1 Notes: No notes.
DMC0_DQ02	I/O	B	none	none	none	none	none	VDD_DMC	Desc: DMC0 Data 2 Notes: No notes.
DMC0_DQ03	I/O	B	none	none	none	none	none	VDD_DMC	Desc: DMC0 Data 3 Notes: No notes.
DMC0_DQ04	I/O	B	none	none	none	none	none	VDD_DMC	Desc: DMC0 Data 4 Notes: No notes.
DMC0_DQ05	I/O	B	none	none	none	none	none	VDD_DMC	Desc: DMC0 Data 5 Notes: No notes.
DMC0_DQ06	I/O	B	none	none	none	none	none	VDD_DMC	Desc: DMC0 Data 6 Notes: No notes.
DMC0_DQ07	I/O	B	none	none	none	none	none	VDD_DMC	Desc: DMC0 Data 7 Notes: No notes.

Table 15. ADSP-BF70x Designer Quick Reference (Continued)

Signal Name	Type	Driver Type	Int Term	Reset Term	Reset Drive	Hiber Term	Hiber Drive	Power Domain	Description and Notes
TWI0_SCL	I/O	D	none	none	none	none	none	VDD_EXT	Desc: TWI0 Serial Clock Notes: Open drain, requires external pull up. Consult version 2.1 of the I2C specification for the proper resistor value. If TWI is not used, connect to ground.
TWI0_SDA	I/O	D	none	none	none	none	none	VDD_EXT	Desc: TWI0 Serial Data Notes: Open drain, requires external pull up. Consult version 2.1 of the I2C specification for the proper resistor value. If TWI is not used, connect to ground.
USB0_CLKIN	a	na	none	none	none	none	none	VDD_USB	Desc: USB0 Clock/Crystal Input Notes: If USB is not used, connect to ground. Active during reset
USB0_DM	I/O	F	none	none	none	none	none	VDD_USB	Desc: USB0 Data – Notes: Pull low if not using USB. For complete documentation of hibernate behavior when USB is used, see the USB chapter in the HRM.
USB0_DP	I/O	F	none	none	none	none	none	VDD_USB	Desc: USB0 Data + Notes: Pull low if not using USB. For complete documentation of hibernate behavior when USB is used, see the USB chapter in the HRM.
USB0_ID	I/O	na	none	none	none	none	none	VDD_USB	Desc: USB0 OTG ID Notes: If USB is not used connect to ground. When USB is being used, the internal pull-up that is present during hibernate is programmable. See the USB chapter in the HRM. Active during reset.
USB0_VBC	I/O	E	none	none	none	none	none	VDD_USB	Desc: USB0 VBUS Control Notes: If USB is not, used pull low.
USB0_VBUS	I/O	G	none	none	none	none	none	VDD_USB	Desc: USB0 Bus Voltage Notes: If USB is not used, connect to ground.
USB0_XTAL	a	na	none	none	none	none	none	VDD_USB	Desc: USB0 Crystal Notes: No notes.
VDD_DMC	s	na	none	none	none	none	none	na	Desc: VDD for DMC Notes: If the DMC is not used, connect to VDD_INT.
VDD_EXT	s	na	none	none	none	none	none	na	Desc: External VDD Notes: Must be powered.
VDD_HADC	s	na	none	none	none	none	none	na	Desc: VDD for HADC Notes: If HADC is not used, connect to ground.
VDD_INT	s	na	none	none	none	none	none	na	Desc: Internal VDD Notes: Must be powered.

TIMING SPECIFICATIONS

Specifications are subject to change without notice.

Clock and Reset Timing

Table 29 and Figure 8 describe clock and reset operations related to the clock generation unit (CGU). Per the CCLK, SYSCLK, SCLK0, SCLK1, DCLK, and OCLK timing specifications in Table 17 on Page 51 and Table 18 on Page 52, combinations of SYS_CLKIN and clock multipliers must not select clock rates in excess of the processor's maximum instruction rate.

Table 29. Clock and Reset Timing

Parameter		V_{DD_EXT} 1.8 V Nominal Min	V_{DD_EXT} 1.8 V Nominal Max	V_{DD_EXT} 3.3 V Nominal Min	V_{DD_EXT} 3.3 V Nominal Max	Unit
Timing Requirement						
f_{CKIN}	SYS_CLKIN Crystal Frequency (CGU_CTL.DF = 0)[1, 2, 3]	19.2	35	19.2	50	MHz
f_{CKIN}	SYS_CLKIN Crystal Frequency (CGU_CTL.DF = 1)[1, 2, 3]	N/A	N/A	38.4	50	MHz
f_{CKIN}	SYS_CLKIN External Source Frequency (CGU_CTL.DF = 0)[1, 2, 3]	19.2	60	19.2	60	MHz
f_{CKIN}	SYS_CLKIN External Source Frequency (CGU_CTL.DF = 1)[1, 2, 3]	38.4	60	38.4	60	MHz
t_{CKINL}	SYS_CLKIN Low Pulse[1]	8.33		8.33		ns
t_{CKINH}	SYS_CLKIN High Pulse[1]	8.33		8.33		ns
t_{WRST}	$\overline{\text{SYS\_HWRST}}$ Asserted Pulse Width Low[4]	11 × t_{CKIN}		11 × t_{CKIN}		ns

[1] Applies to PLL bypass mode and PLL nonbypass mode.
[2] The t_{CKIN} period (see Figure 8) equals $1/f_{CKIN}$.
[3] Combinations of the CLKIN frequency and the PLL clock multiplier must not exceed the allowed f_{PLLCLK} setting discussed in Table 19.
[4] Applies after power-up sequence is complete. See Table 30 and Figure 9 for power-up reset timing.

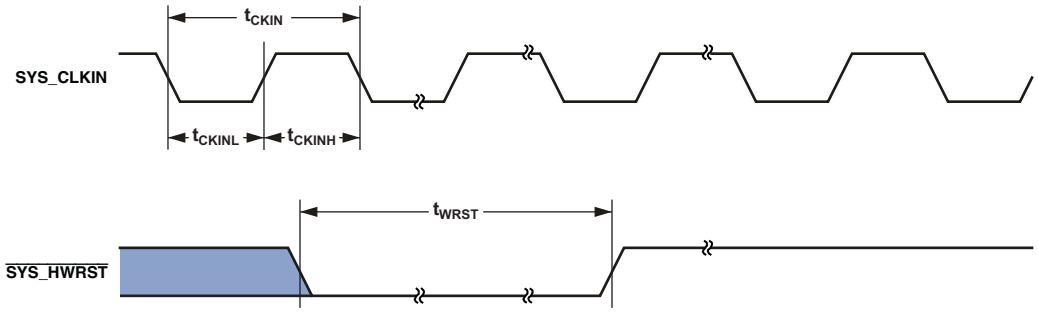


Figure 8. Clock and Reset Timing

DDR2 SDRAM Read Cycle Timing

Table 40 and Figure 18 show DDR2 SDRAM read cycle timing, related to the dynamic memory controller (DMC).

Table 40. DDR2 SDRAM Read Cycle Timing, V_{DD_DMC} Nominal 1.8 V

Parameter		200 MHz[1] Min	Max	Unit
Timing Requirements				
t_{DQSQ}	DMC0_DQS-DMC0_DQ Skew for DMC0_DQS and Associated DMC0_DQ Signals		0.35	ns
t_{QH}	DMC0_DQ, DMC0_DQS Output Hold Time From DMC0_DQS	1.8		ns
t_{RPRE}	Read Preamble	0.9		t_{CK}
t_{RPST}	Read Postamble	0.4		t_{CK}

[1] To ensure proper operation of the DDR2, all the DDR2 guidelines have to be strictly followed.

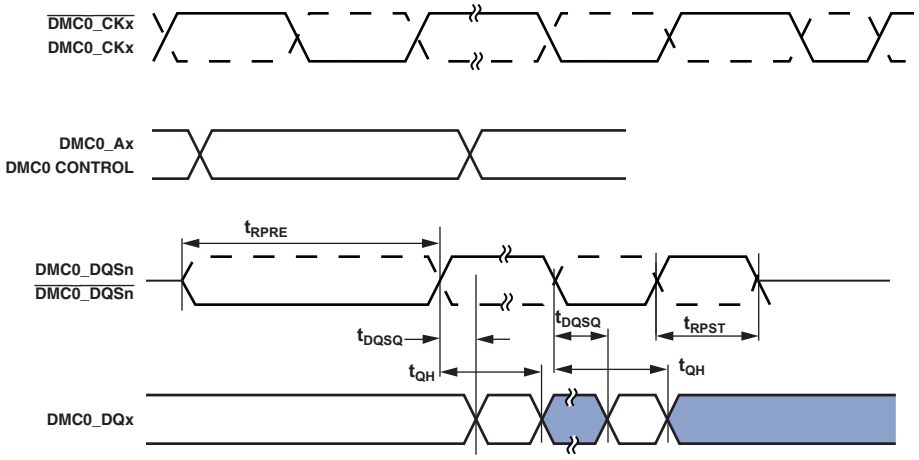


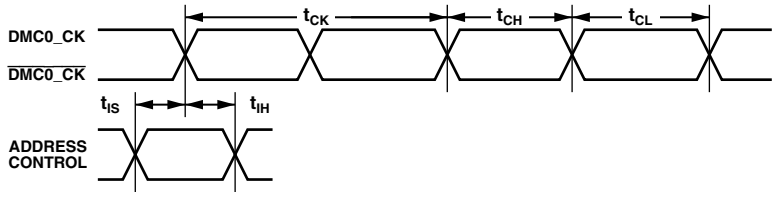
Figure 18. DDR2 SDRAM Controller Input AC Timing

Mobile DDR SDRAM Clock and Control Cycle Timing

Table 42 and Figure 20 show mobile DDR SDRAM clock and control cycle timing, related to the dynamic memory controller (DMC).

Table 42. Mobile DDR SDRAM Clock and Control Cycle Timing, V_{DD_DMC} Nominal 1.8 V

Parameter		200 MHz Min	200 MHz Max	Unit
Switching Characteristics				
t_{CK}	Clock Cycle Time (CL = 2 Not Supported)	5		ns
t_{CH}	Minimum Clock Pulse Width	0.45	0.55	t_{CK}
t_{CL}	Maximum Clock Pulse Width	0.45	0.55	t_{CK}
t_{IS}	Control/Address Setup Relative to DMC0_CK Rise	1.5		ns
t_{IH}	Control/Address Hold Relative to DMC0_CK Rise	1.5		ns



NOTE: CONTROL = $\overline{\text{DMC0\_CS0}}$, DMC0_CKE, $\overline{\text{DMC0\_RAS}}$, $\overline{\text{DMC0\_CAS}}$, AND $\overline{\text{DMC0\_WE}}$.
ADDRESS = DMC0_A00–13, AND DMC0_BA0–2.

Figure 20. Mobile DDR SDRAM Clock and Control Cycle Timing

Mobile DDR SDRAM Read Cycle Timing

Table 43 and Figure 21 show mobile DDR SDRAM read cycle timing, related to the dynamic memory controller (DMC).

Table 43. Mobile DDR SDRAM Read Cycle Timing, V_{DD_DMC} Nominal 1.8 V

Parameter		200 MHz		Unit
		Min	Max	
Timing Requirements				
t_{QH}	DMC0_DQ, DMC0_DQS Output Hold Time From DMC0_DQS	1.5		ns
t_{DQSQ}	DMC0_DQS-DMC0_DQ Skew for DMC0_DQS and Associated DMC0_DQ Signals		0.7	ns
t_{RPRE}	Read Preamble	0.9	1.1	t_{CK}
t_{RPST}	Read Postamble	0.4	0.6	t_{CK}

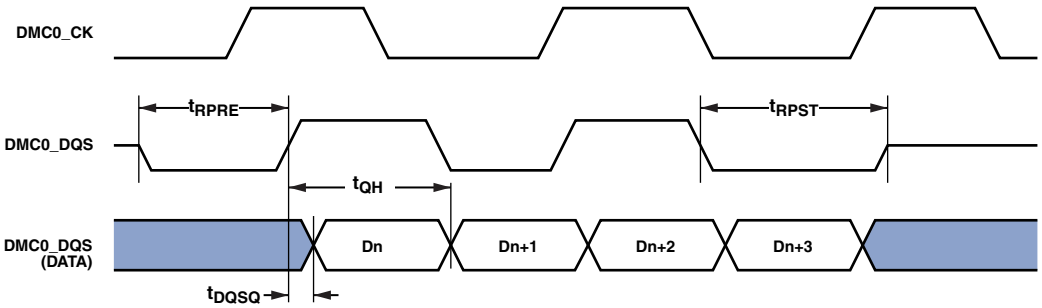


Figure 21. Mobile DDR SDRAM Controller Input AC Timing

Table 51. Serial Ports—Enable and Three-State

Parameter		V_{DD_EXT} 1.8 V Nominal Min	V_{DD_EXT} 1.8 V Nominal Max	V_{DD_EXT} 3.3 V Nominal Min	V_{DD_EXT} 3.3 V Nominal Max	Unit
Switching Characteristics						
t_{DDTEN}	Data Enable from External Transmit SPT_CLK[1]	1		1		ns
t_{DDTTE}	Data Disable from External Transmit SPT_CLK[1]		14		14	ns
t_{DDTIN}	Data Enable from Internal Transmit SPT_CLK[1]	–1.12		–1		ns
t_{DDTTI}	Data Disable from Internal Transmit SPT_CLK[1]		2.8		2.8	ns

[1] Referenced to drive edge.

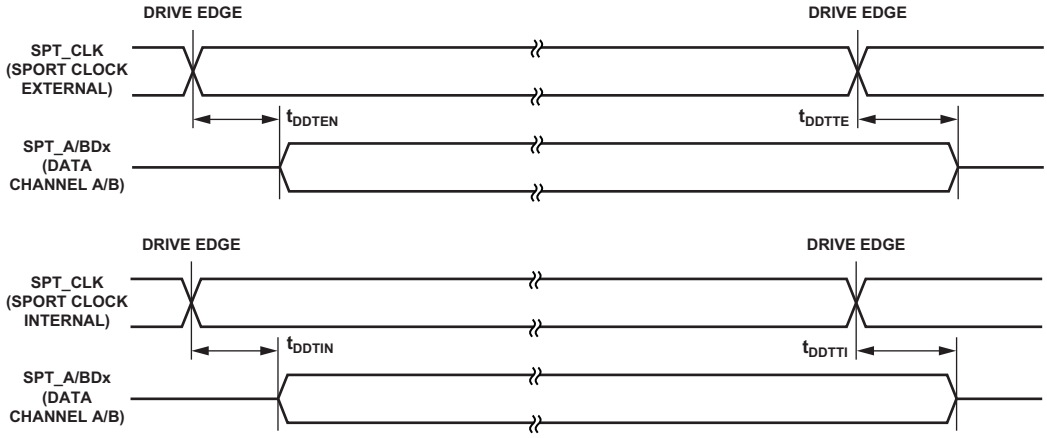


Figure 28. Serial Ports—Enable and Three-State

Serial Peripheral Interface (SPI) Port—Open Drain Mode (ODM) Timing

In Figure 35 and Figure 36, the outputs can be SPI_MOSI SPI_MISO, SPI_D2, and/or SPI_D3 depending on the mode of operation.

Table 57. SPI Port ODM Master Mode Timing

Parameter		V_{DD_EXT} 1.8 V Nominal Min	V_{DD_EXT} 1.8 V Nominal Max	V_{DD_EXT} 3.3 V Nominal Min	V_{DD_EXT} 3.3 V Nominal Max	Unit
Switching Characteristics						
$t_{HDSPIODMM}$	SPI_CLK Edge to High Impedance from Data Out Valid	–4.5		–3.5		ns
$t_{DDSPIODMM}$	SPI_CLK Edge to Data Out Valid from High Impedance		2.5		2	ns

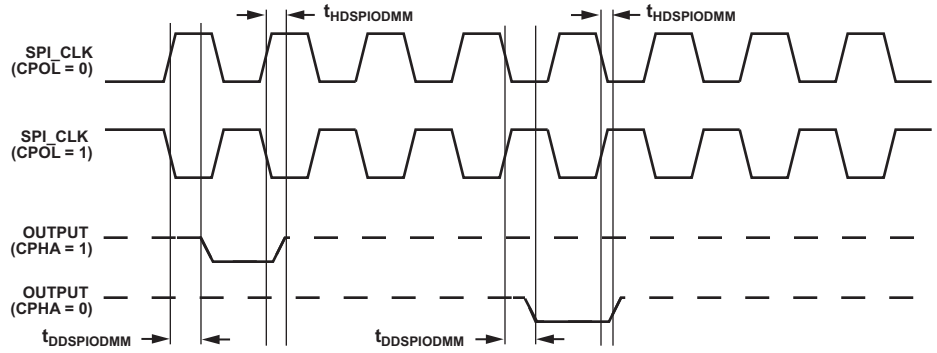


Figure 35. ODM Master

Serial Peripheral Interface (SPI) Port—SPI_RDY Timing

SPI_RDY is used to provide flow control. The CPOL and CPHA bits are set in SPI_CTL, while LEADX, LAGX, and STOP are in SPI_DLY.

Table 59. SPI Port—SPI_RDY Timing

Parameter		V_{DD_EXT} 1.8 V/3.3 V Nominal Min	Max	Unit
Timing Requirements				
$t_{SRDYSCKM0}$	Minimum Setup Time for SPI_RDY De-assertion in Master Mode Before Last SPI_CLK Edge of Valid Data Transfer to Block Subsequent Transfer with CPHA = 0	$(2.5 + 1.5 \times BAUD^{1}) \times t_{SCLK0} + 14.5$		ns
$t_{SRDYSCKM1}$	Minimum Setup Time for SPI_RDY De-assertion in Master Mode Before Last SPI_CLK Edge of Valid Data Transfer to Block Subsequent Transfer with CPHA = 1	$(2.5 + BAUD^{1}) \times t_{SCLK0} + 14.5$		ns
Switching Characteristic				
$t_{SRDYSCKM}$	Time Between Assertion of SPI_RDY by Slave and First Edge of SPI_CLK for New SPI Transfer with CPHA = 0 and BAUD = 0 (STOP, LEADX, LAGX = 0)	$3 \times t_{SCLK0}$	$4 \times t_{SCLK0} + 17.5$	ns
	Time Between Assertion of SPI_RDY by Slave and First Edge of SPI_CLK for New SPI Transfer with CPHA = 0 and BAUD ≥ 1 (STOP, LEADX, LAGX = 0)	$(4 + 1.5 \times BAUD^{1}) \times t_{SCLK0}$	$(5 + 1.5 \times BAUD^{1}) \times t_{SCLK0} + 17.5$	ns
	Time Between Assertion of SPI_RDY by Slave and First Edge of SPI_CLK for New SPI Transfer with CPHA = 1 (STOP, LEADX, LAGX = 0)	$(3 + 0.5 \times BAUD^{1}) \times t_{SCLK0}$	$(4 + 0.5 \times BAUD^{1}) \times t_{SCLK0} + 17.5$	ns

[1] BAUD value set using the SPI_CLK.BAUD bits.

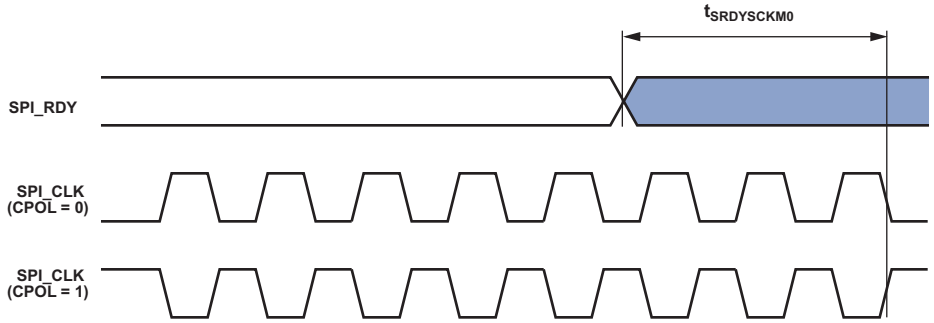


Figure 37. SPI_RDY Setup Before SPI_CLK with CPHA = 0

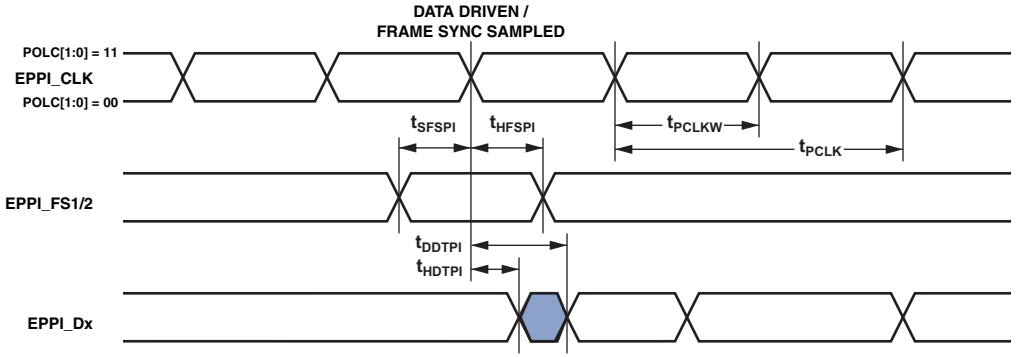


Figure 43. PPI Internal Clock GP Transmit Mode with External Frame Sync Timing

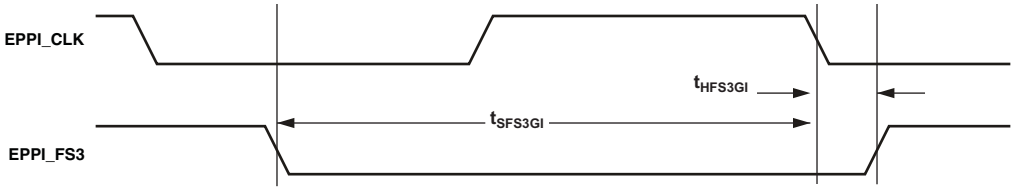


Figure 44. Clock Gating Mode with Internal Clock and External Frame Sync Timing

OUTPUT DRIVE CURRENTS

Figure 50 through Figure 61 show typical current-voltage characteristics for the output drivers of the ADSP-BF70x Blackfin processors. The curves represent the current drive capability of the output drivers as a function of output voltage.

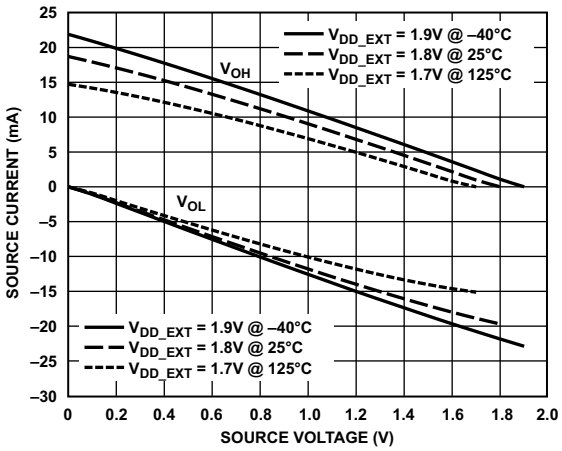


Figure 50. Driver Type A Current (1.8 V V_{DD_EXT})

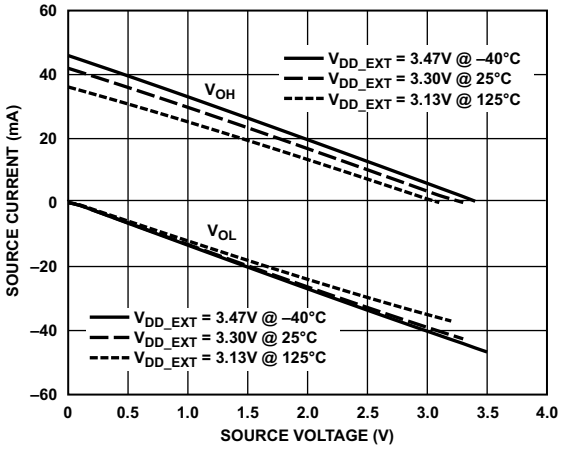


Figure 51. Driver Type A Current (3.3 V V_{DD_EXT})

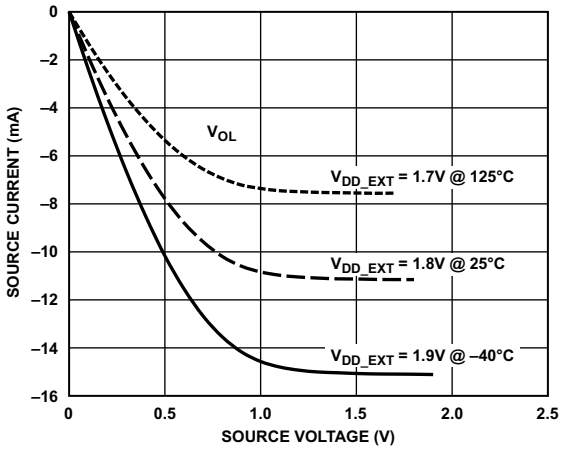


Figure 52. Driver Type D Current (1.8 V V_{DD_EXT})

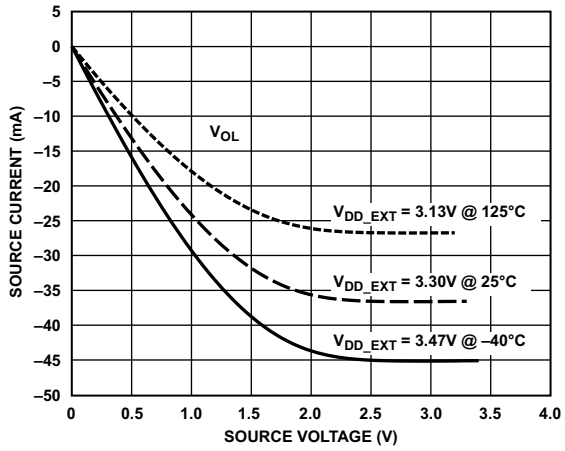


Figure 53. Driver Type D Current (3.3 V V_{DD_EXT})

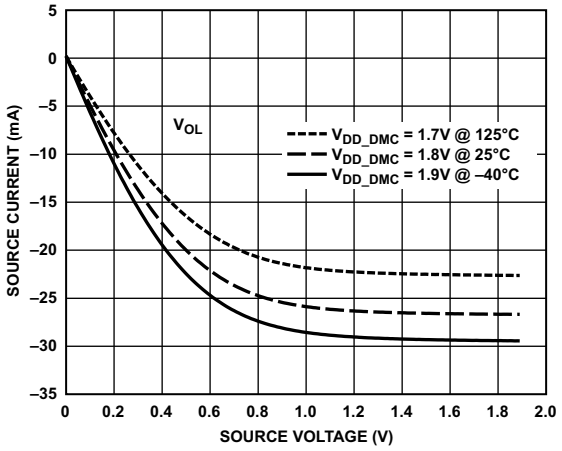


Figure 54. Driver Type B and Driver Type C (DDR Drive Strength 34 Ω)

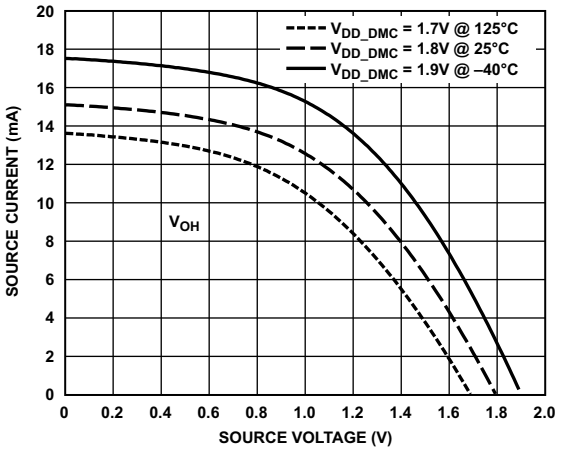


Figure 61. Driver Type B and Device Driver C (DDR Drive Strength 60 Ω)

TEST CONDITIONS

All timing requirements appearing in this data sheet were measured under the conditions described in this section. Figure 62 shows the measurement point for ac measurements (except output enable/disable). The measurement point V_{MEAS} is $V_{DD\_EXT}/2$ for V_{DD_EXT} (nominal) = 1.8 V/3.3 V.

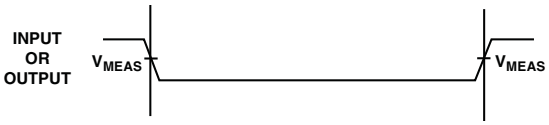


Figure 62. Voltage Reference Levels for AC Measurements (Except Output Enable/Disable)

Output Enable Time Measurement

Output balls are considered to be enabled when they have made a transition from a high impedance state to the point when they start driving.

The output enable time t_{ENA} is the interval from the point when a reference signal reaches a high or low voltage level to the point when the output starts driving as shown on the right side of Figure 63.

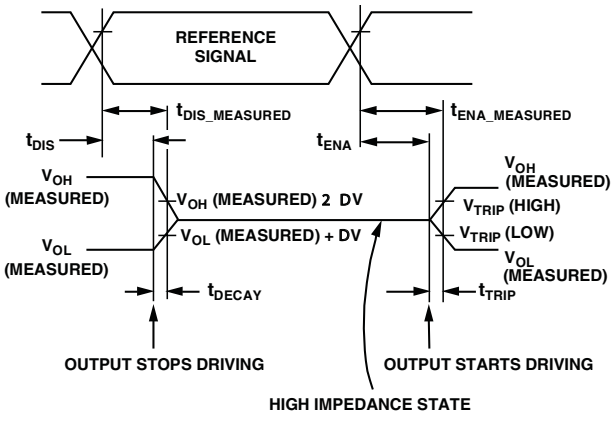


Figure 63. Output Enable/Disable

The time $t_{ENA\_MEASURED}$ is the interval from when the reference signal switches to when the output voltage reaches V_{TRIP} (high) or V_{TRIP} (low). For V_{DD_EXT} (nominal) = 1.8 V, V_{TRIP} (high) is 1.05 V, and V_{TRIP} (low) is 0.75 V. For V_{DD_EXT} (nominal) = 3.3 V, V_{TRIP} (high) is 1.9 V, and V_{TRIP} (low) is 1.4 V. Time t_{TRIP} is the interval from when the output starts driving to when the output reaches the V_{TRIP} (high) or V_{TRIP} (low) trip voltage.

Time t_{ENA} is calculated as shown in the equation:

$$t_{ENA} = t_{ENA\_MEASURED} - t_{TRIP}$$

If multiple balls (such as the data bus) are enabled, the measurement value is that of the first ball to start driving.

Output Disable Time Measurement

Output balls are considered to be disabled when they stop driving, go into a high impedance state, and start to decay from their output high or low voltage. The output disable time t_{DIS} is the difference between $t_{DIS\_MEASURED}$ and t_{DECAY} as shown on the left side of Figure 63.

$$t_{DIS} = t_{DIS\_MEASURED} - t_{DECAY}$$

The time for the voltage on the bus to decay by ΔV is dependent on the capacitive load, C_L and the load current, I_L. This decay time can be approximated by the equation:

$$t_{DECAY} = (C_L \Delta V)/I_L$$

The time t_{DECAY} is calculated with test loads C_L and I_L, and with ΔV equal to 0.25 V for V_{DD_EXT} (nominal) = 3.3 V and 0.15 V for V_{DD_EXT} (nominal) = 1.8V.

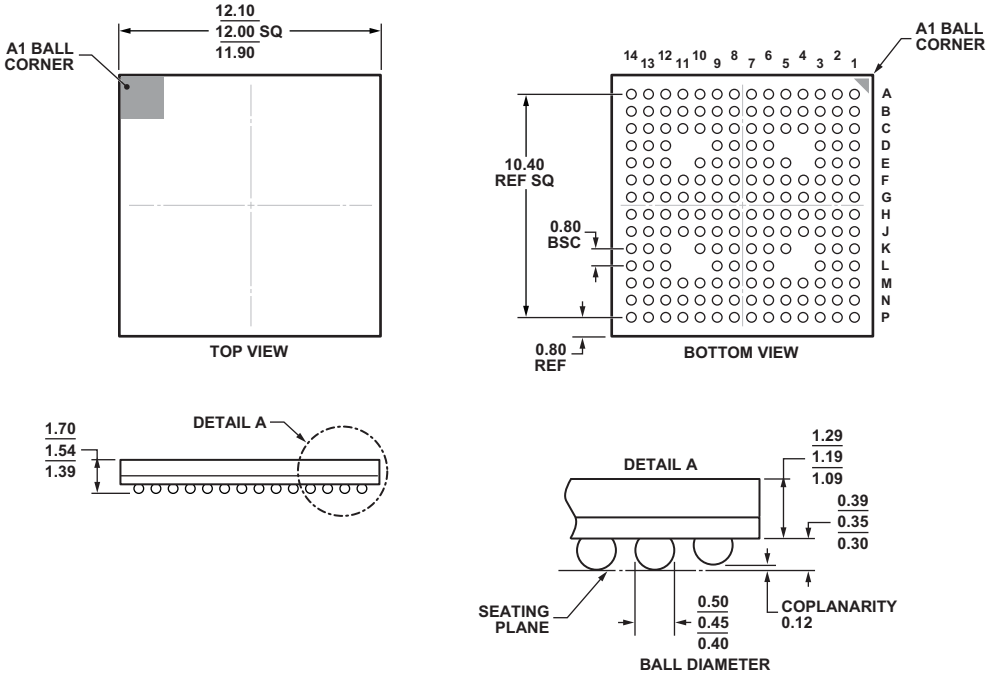
The time $t_{DIS\_MEASURED}$ is the interval from when the reference signal switches, to when the output voltage decays ΔV from the measured output high or output low voltage.

Example System Hold Time Calculation

To determine the data output hold time in a particular system, first calculate t_{DECAY} using the previous equation. Choose ΔV to be the difference between the processor's output voltage and the input threshold for the device requiring the hold time. C_L is the total bus capacitance (per data line), and I_L is the total leakage or three-state current (per data line). The hold time will be t_{DECAY} plus the various output disable times as specified in the Timing Specifications on Page 60.

OUTLINE DIMENSIONS

Dimensions for the 12 mm × 12 mm CSP_BGA package in Figure 71 are shown in millimeters.



COMPLIANT TO JEDEC STANDARDS MO-275-GGAA-1

Figure 71. 184-Ball Chip Scale Package Ball Grid Array [CSP_BGA]
(BC-184-1)
Dimensions shown in millimeters